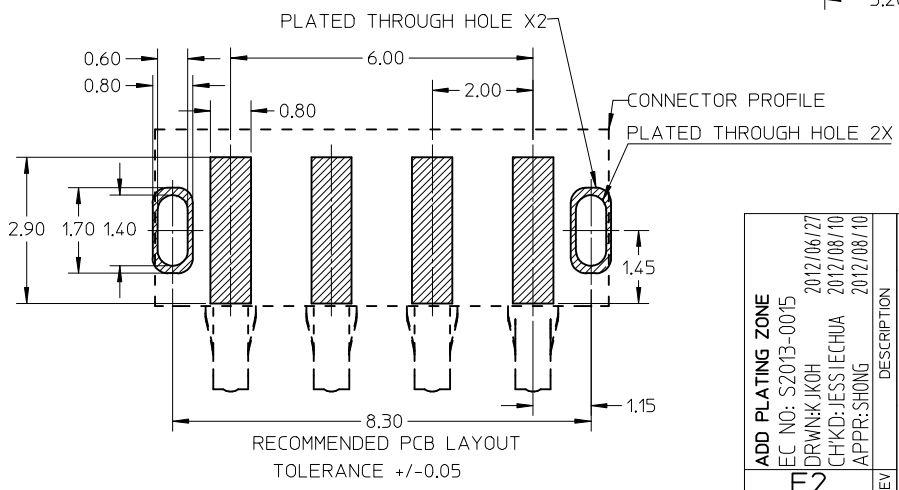
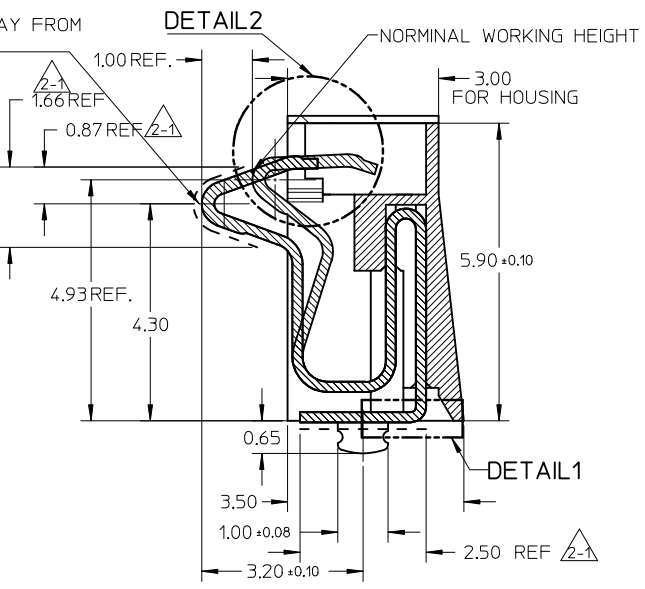
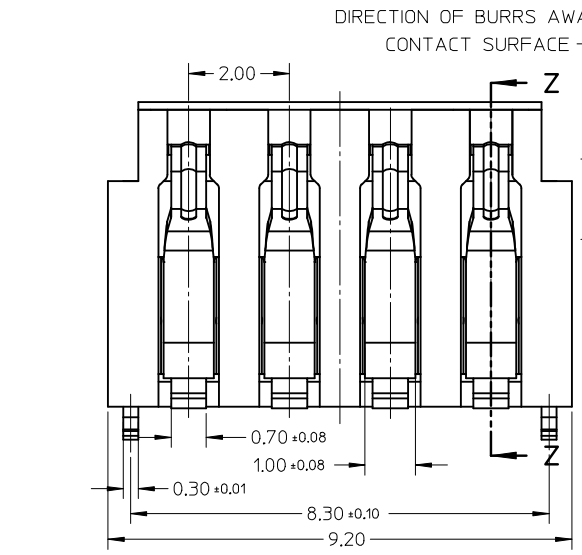
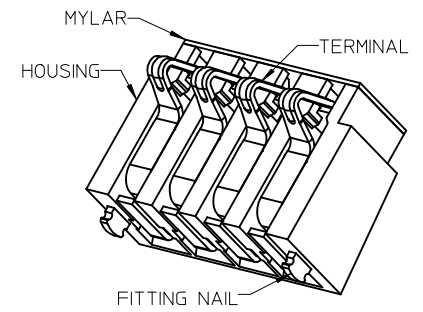
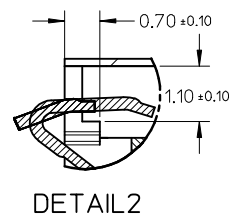
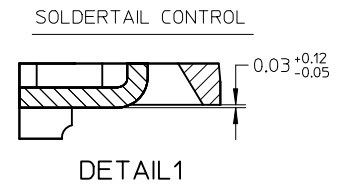
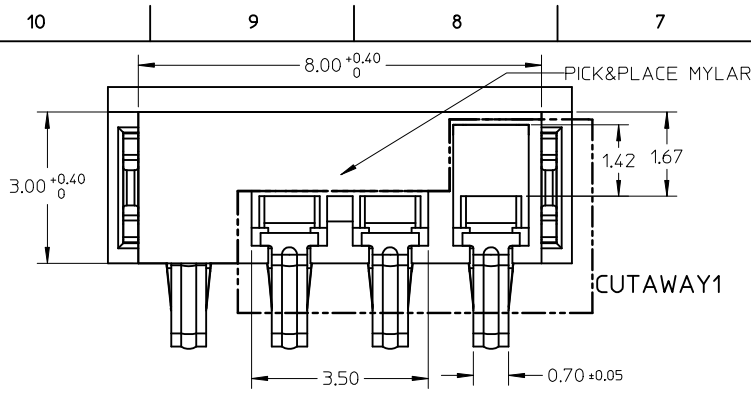


NOTES:

- 1 MATERIAL:
  - 1-1 TERMINAL : BERYLLIUM COPPER, THICKNESS 0.20MM
  - 1-2 HOUSING : HIGH TEMPERATURE THERMAL PLASTIC
  - 1-3 FITTING NAIL : BRASS, THICKNESS 0.30MM
  - 1-4 MYLAR : THICKNESS 0.15MM
- 2 FINISH:
  - 2-1 TERMINAL :
    - 50~150μ NICKEL UNDER PLATED
    - 30μ MIN GOLD PLATING ON CONTACT AREA
    - 3μ MIN GOLD FLASH ON SOLDERING AREA
  - 2-2 FITTING NAIL :
    - 50~200μ NICKEL UNDER PLATED
    - 100~200μ TIN PLATED ON SOLDERING AREA
- 3 MECHANICAL SPECIFICATION:
  - 3-1 FORCE : 135±25g/ 0.7mm AWAY FROM HOUSING SURFACE
  - 3-2 MATING CYCLES : 10,000 TIMES
- 4 ELECTRICAL SPECIFICATION:
  - 4-1 RATED VOLTAGE : 200 VOLTS RMS MAX.
  - 4-2 RATED CURRENT : 1.5 AMPS CONTINUOUS AND 2 AMPS PULSES
  - 4-3 CONTACT RESISTANCE : 25 MILLIOHMS MAX.
- 5 ADHIBIT MYLAR AFTER ASSEMBLY PROCESS
- 6 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

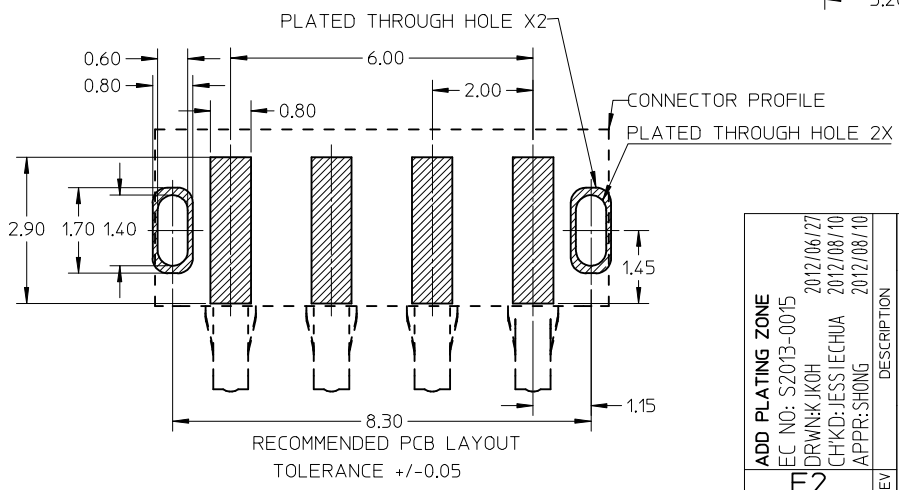


ADD PLATING ZONE EC NO: S2013-0015 DRW: JAKH CHK: JESSIE CHUA APPR: SHONG	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>	SCALE <b>10:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± --- ± ---	mm INCH DRAWN BY: XU XIANG CHECKED BY: XU XIANG APPROVED BY: JNCHEN	DATE: 2006-06-29 DATE: 2007/03/14 DATE: 2007/03/19	TITLE: 2.0MM PITCH 4 PINS T/H SIDE CONTACT BATTERY CONN.	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47507-001	SHEET NO. 1 OF 1
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		REV: F2	DESCRIPTION:	MOLEX INCORPORATED				



NOTES:

- 1 MATERIAL:
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- 5 ADHIBIT MYLAR AFTER ASSEMBLY PROCESS
- 6 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



ADD PLATING ZONE EC NO: S2013-0015 DRW/K: JKH CHK/D: JESSIE CHUA APPR: SHONG	2012/06/27 2012/08/10 2012/08/10	DESCRIPTION F2	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			▽=0	mm INCH	MM ONLY	10:1	METRIC	⊙ □	
			∇=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE	2.0MM PITCH 4 PINS T/H SIDE CONTACT BATTERY CONN.		
				3 PLACES ± --- ± ---	XU XIANG 2006-06-29				
	2 PLACES ± 0.15 ± ---	CHECKED BY DATE		MOLEX INCORPORATED MOLEX					
	1 PLACE ± --- ± ---	XU XIANG 2007/03/14							
	ANGULAR ± --- °	APPROVED BY DATE		MATERIAL NO. DOCUMENT NO. SHEET NO. SEE TABLE SD-47507-001 1 OF 1					
		JNCHEN 2007/03/19							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				A3					